CERTIFICATE

The Certification Body of TÜV SÜD PSB Pte Ltd

certifies that

STATS CHIPPAC PTE LTD

5 Yishun Street 23 Singapore 768442

has established and applies a Quality Management System for

- 1. Design and Development of ICs Package and Test Hardware and Software
- 2. Wafer Sort, Wafer Process, Assembly and Test of ICs
- 3. Packages WLCSP (Wafer Level Chip Scale Packages), Bump and Integrated Passive Device and eWLB (Embedded Wafer Level **Ball Grid Array)**

(See Appendix to Certificate for Details)

Proof has been furnished that the requirements according to

ISO 9001: 2015

are fulfilled. The certificate is valid from 2018-08-23 to 2021-08-22 Certificate Registration No. 96-2-0622

Date of Print: 2018-08-24



SIEW Kwai Heng, Tiffany Certification Manager **Business Assurance Division** Management Systems



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TÜV SÜD PSB 08/07.02

APPENDIX

To Certificate Number: 96-2-0622

Issue Number:

Ö

Date of Print:

2018-08-24

Issued to:

STATS CHIPPAC PTE LTD

5 Yishun Street 23 Singapore 768442

Process or service in respect of which the company is Certified:

- 1. Design and Development of ICs Package and Test Hardware and Software
- 2. Wafer Sort, Wafer Process, Assembly and Test of ICs
- 3. Packages WLCSP (Wafer Level Chip Scale Packages), Bump and Integrated Passive Device and eWLB (Embedded Wafer Level Ball Grid Array)

Process Detail(s)/Location(s):

The scope of certification covers the following:

Divisions/ Locations	Supporting Functions
Stats ChipPac Pte Ltd 10 Ang Mo Kio Street 65, Techpoint, #04-08/09 Singapore 569059	Contract Review



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SIEW Kwai Heng, Tiffany Certification Manager Business Assurance Division Management Systems



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